

09-20-2001

HEET

U.S. DEPARTMENT OF COMMERCE  
Patent and Trademark Office

101850194

To the Honorable Assistant Secretary and  
or copy(ies) thereof.

Please record the attached original document(s)

## 1. Name of conveying party(ies):

Yoshinori SAKAI; Kazuhiro NOBORI; and  
Kazuo ARISUE

Additional name(s) of conveying party(ies) attached? No

## 3. Nature of conveyance:

9-14-01

☒ Assignment ☐ Merger  
☐ Security Agreement ☐ Change of Name  
☐ Other

Execution Date: May 8 and May 14, 2001

## 2. Name and address of receiving party(ies):

Name: Matsushita Electric Industrial Co., Ltd.Street Address: 1006, Oaza Kadoma, Kadoma-shi  
Osaka-fu, Japan

Additional name(s) &amp; address(es) attached? No

## 4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is:

A. Patent Application No.(s)  
09/814,964B. Patent No.(s)  
, issued

Additional numbers attached? No

5. Name and address of party to whom correspondence  
concerning document should be mailed:Name: WENDEROTH, LIND & PONACK, L.L.P.  
Attn: Michael S. Huppert, Esq.Street Address: 2033 K Street, N.W., Suite 800City: Washington, State: DC ZIP: 20006-10216. Total number of applications and patents involved: 1

## 7. Total fee (37 CFR 3.41). . . . . \$40.00

☒ Enclosed (Check No. 44457)  
Authorized to be charged to deposit account8. Deposit account number: 23-0975

(Attach duplicate copy of this page if paying by deposit account)

DO NOT USE THIS SPACE

## 9. Statement and signature.

*To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.*Michael S. Huppert, Reg. No. 40,268  
Name of Person SigningMichael Huppert  
SignatureSeptember 14, 2001  
DateTotal number of pages including cover sheet: 3

OMB No. 0651-0011 (exp. 4/94)

Do not detach this portion

09/19/2001 TDIAZ1 00000156 09814964

01 FC:581 40.00 DP

Mail documents to be recorded with required cover sheet information:

Commissioner and Assistant Secretary of Patents and Trademarks  
Box Assignments  
Washington, D.C. 2023140E  
THE COMMISSIONER IS AUTHORIZED  
TO CHARGE ANY DEFICIENCY IN THE  
FEE FOR THIS PAPER TO DEPOSIT  
ACCOUNT NO. 23-0975.

Public burden reporting for this sample cover sheet is estimated to average about 30 minutes per document to be recorded, including time for reviewing the document and gathering the data needed, and completing and reviewing the sample cover sheet. Send comments regarding this burden estimate to the U.S. Patent and Trademark Office, Office of Information Systems, PK2-1000C, Washington, D.C. 20231, and the Office of Management and Budget, Paperwork Reduction Project (0651-0011), Washington, D.C. 20503.

# ASSIGNMENT

In consideration of the sum of One Dollar (\$1.00) and other good and valuable consideration paid to each of the undersigned

Yoshinori SAKAI,

Kazuhiro NOBORI, and

Insert Name(s)  
of Inventor(s)

Kazuo ARISUE

the undersigned hereby sell(s) and assign(s) to

Insert Name(s)  
of Assignee(s)

Matsushita Electric Industrial Co., Ltd.

Address

of 1006, Oaza Kadoma, Kadoma-shi, Osaka-fu, Japan

(hereinafter designated as the Assignee) the entire right, title and interest for the United States as defined in 35 USC 100, in the invention known as

Title of  
Invention

SEMICONDUCTOR PACKAGE AND METHOD OF MANUFACTURING

SEMICONDUCTOR PACKAGE

Date of Signing  
of Application

for which an application for patent in the United States has been executed by the undersigned on

May 14, May 8, and May 8, 2001, respectively.

The undersigned agree(s) to execute all papers necessary in connection with this application and any continuing, divisional or reissue applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

The undersigned agree(s) to execute all papers necessary in connection with any interference which may be declared concerning this application or continuation, division or reissue thereof and to cooperate with the Assignee in every way possible in obtaining evidence and going forward with such interference.

The undersigned agree(s) to execute all papers and documents and perform any act which may be necessary in connection with claims or provisions of the International Convention for Protection of Industrial Property or similar agreements.

The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States patent to the Assignee.

The undersigned hereby authorize(s) and request(s) the Commissioner of Patents to issue any and all Letters Patents of the United States resulting from said application or any division or divisions or continuing or reissue applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) full right to convey the entire interest herein assigned, and that he has (they have) not executed, and will not execute, any agreement in conflict herewith.

The undersigned hereby grant(s) the firm of WENDEROTH, LIND & PONACK, L.L.P., 2033 K Street, N.W., Suite 800, Washington, DC 20006, the power to insert on this assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent Office for recordation of this document.

In witness whereof, executed by the undersigned on the date(s) opposite the undersigned name(s).

Date 14.5.2001, Name of Inventor Yoshinori Sakai  
YOSHINORI SAKAI

Date 08.5.2001, Name of Inventor Kazuhiko Nobori  
KAZUHIRO NOBORI

Date 08.5.2001, Name of Inventor Kazuo Arisue  
KAZUO ARISUE

Date \_\_\_\_\_, Name of Inventor \_\_\_\_\_

Date \_\_\_\_\_, Name of Inventor \_\_\_\_\_

Date \_\_\_\_\_, Name of Inventor \_\_\_\_\_

(This assignment should preferably be acknowledged before a United States Consul. If not, then the execution by the Inventor(s) should be witnessed by at least two witnesses who sign here.)

Witness Setsumi Horimoto

Witness Mihiko Nakata

### ACKNOWLEDGEMENT

\_\_\_\_\_  
\_\_\_\_\_  
}

ss

This \_\_\_\_\_ day of \_\_\_\_\_, \_\_\_\_\_, before me  
personally came the above-named \_\_\_\_\_

to me personally known as the individual(s) who executed the foregoing assignment, who did acknowledge to me that he (they) executed the same of his (their) own free will for the purposes therein set forth.

SEAL

\_\_\_\_\_  
Official Signature

\_\_\_\_\_  
Official Title

The above application may be more particularly identified as follows:

U.S. Application Serial No. \_\_\_\_\_ Filing Date March 23, 2001  
Applicant Reference Number 533279 Atty Docket No. 2001\_0346A  
Title of Invention SEMICONDUCTOR PACKAGE AND METHOD OF MANUFACTURING  
SEMICONDUCTOR PACKAGE